

Title (en)
PLASMA ENHANCED ATOMIC LAYER DEPOSITION (PEALD) EQUIPMENT AND METHOD OF FORMING A CONDUCTING THIN FILM USING THE SAME THEREOF

Title (de)
GERÄTE FÜR DIE PLASMAVERSTÄRKTE ATOMISCHE SCHICHTABLAGERUNG (PEALD) UND VERFAHREN ZUR BILDUNG EINES DÜNNEN LEITFÄHIGEN FILMS DAMIT DAFÜR

Title (fr)
APPAREIL DE DEPOT DE COUCHE ATOMIQUE ACTIVE PAR PLASMA (PEALD) ET PROCEDE DE FORMATION D'UN FILM MINCE A L'AIDE DUDIT APPAREIL

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Application
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Abstract (en)
[origin: WO03023835A1] A plasma enhanced atomic layer deposition (PEALD) apparatus and a method of forming a conductive thin film using the same are disclosed. According to the present invention of a PEALD apparatus and a method, a process gas inlet tube and a process gas outlet tube are installed symmetrically and concentrically with respect to a substrate, thereby allowing the process gas to flow uniformly, evenly and smoothly over the substrate, thereby forming a thin film uniformly over the substrate. A uniquely designed showerhead assembly provides not only reduces the volume of the reactor space, but also allows the process gases to flow uniformly, evenly and smoothly throughout the reaction space area and reduces the volume of the reaction space, and the smaller volume makes it easier and fast to change the process gases for sequential and repeated process operation.

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